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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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Silicon N-Channel MOS FET



ADE-208-1352 (Z) 1st. Edition Mar. 2001

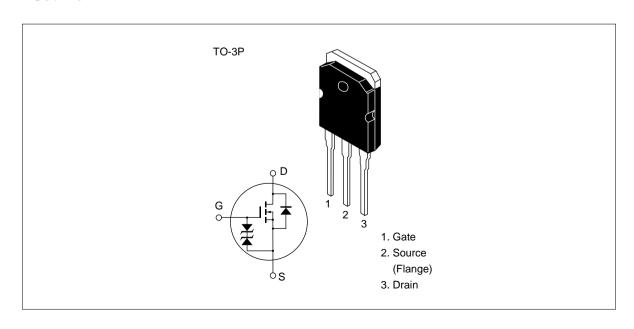
Application

Low frequency power amplifier Complementary pair with 2SJ351, 2SJ352

Features

- High power gain
- Excellent frequency response
- High speed switching
- Wide area of safe operation
- Enhancement-mode
- Good complementary characteristics
- Equipped with gate protection diodes

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Ratings	Unit	
Drain to source voltage	2SK2220	V _{DSX}	180	V	
	2SK2221		200		
Gate to source voltage		V _{GSS}	±20	V	
Drain current		I _D	8	А	
Body to drain diode reverse dr	I _{DR}	8	А		
Channel dissipation		Pch*1	100	W	
Channel temperature		Tch	150	°C	
Storage temperature		Tstg	-55 to +150	°C	
_	_				

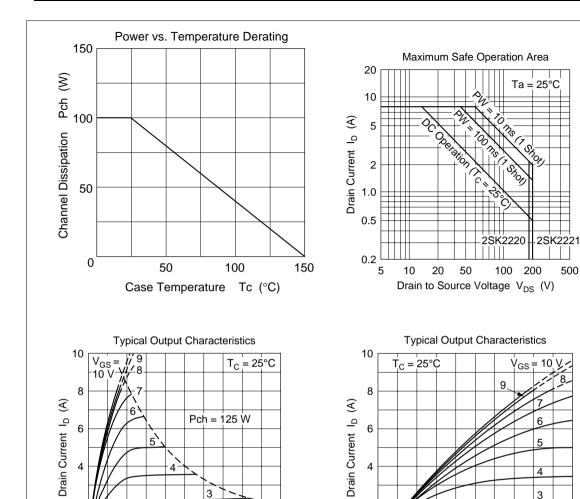
Note 1. Value at Tc = 25 °C

Electrical Characteristics ($Ta = 25^{\circ}C$)

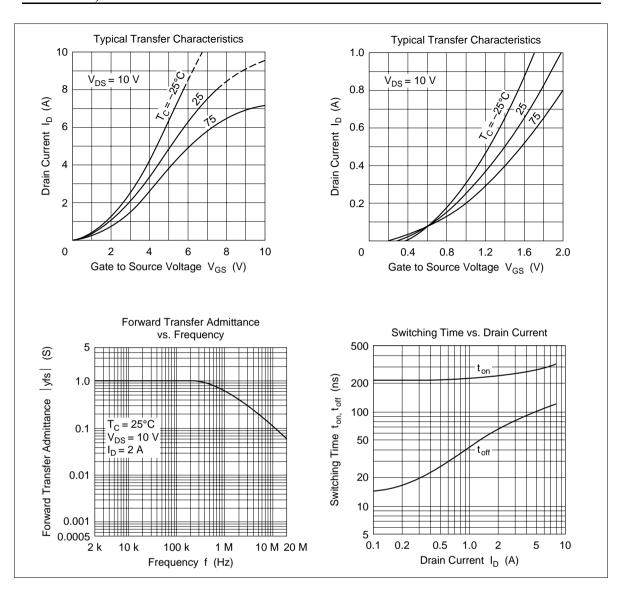
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK2220	$V_{(BR)DSX}$	180	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = -10 \text{ V}$
breakdown voltage	2SK2221		200	_	_		
Gate to source b voltage	reakdown	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source c	utoff voltage	$V_{\text{GS(off)}}$	0.15	_	1.45	V	I _D = 100 mA V _{DS} = 10 V
Drain to source s	aturation	V _{DS(sat)}	_	_	12	V	$I_D = 8 \text{ A}, V_{GD} = 0 \text{ V}^{*1}$
Forward transfer	admittance	y _{fs}	0.7	1.0	1.4	S	I _D = 3 A V _{DS} = 10 V* ¹
Input capacitance	Э	Ciss	_	600	_	pF	V _{GS} = -5 V
Output capacitan	ice	Coss	_	800	_	pF	V _{DS} = 10 V
Reverse transfer	capacitance	Crss	_	8	_	pF	f = 1 MHz
Turn-on time		t _{on}	_	250	_	ns	V _{DD} = 30 V
Turn-off time		t _{off}	_	90	_	ns	$I_D = 4 A$

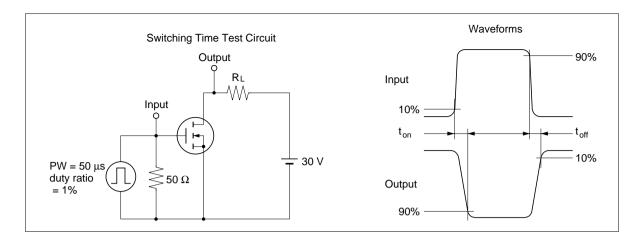
Note 1. Pulse Test

Drain to Source Voltage V_{DS} (V)

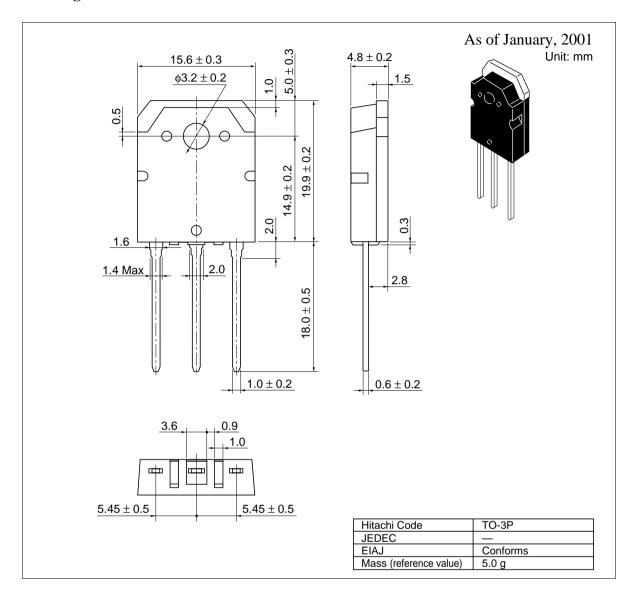


Drain to Source Voltage V_{DS} (V)





Package Dimensions



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